



Description

JMT N-channel Enhancement Mode Power MOSFET

Features

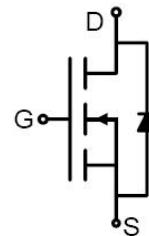
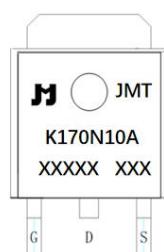
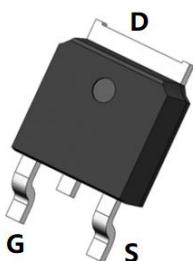
- 100V,59A
- $R_{DS(ON)} < 20m\Omega$ @ $V_{GS} = 10V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead free product is acquired

Application

- Load Switch
- PWM Application
- Power management



100% UIS TESTED!
100% ΔV_{ds} TESTED!



TO-252-4R(DPAK) top view

Marking and pin Assignment

Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	TUBE (PCS)	Inner BOX (PCS)	Per Carton (PCS)
JMTK170N10A	JMTK170N10A	TAPING	TO-252-4R	13inch	2500	25000

Absolute Maximum Ratings ($T_c = 25^\circ C$ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		100	V
V_{GSS}	Gate-Source Voltage		± 25	V
I_D	Continuous Drain Current	$T_c = 25^\circ C$	59	A
		$T_c = 100^\circ C$	38	A
I_{DM}	Pulsed Drain Current ^{note1}		236	A
E_{AS}	Single Pulsed Avalanche Energy ^{note2}		98	mJ
P_D	Power Dissipation	$T_c = 25^\circ C$	153	W
R_{eJC}	Thermal Resistance, Junction to Case		0.98	$^\circ C/W$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +175	$^\circ C$

**Electrical Characteristics** ($T_C=25^\circ C$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristics						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	100	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=100V, V_{GS}=0V,$	-	-	1.0	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 25V$	-	-	± 100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2	3	4	V
$R_{DS(on)}$	Static Drain-Source on-Resistance note3	$V_{GS}=10V, I_D=30A$	-	15	20	$m\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=25V, V_{GS}=0V,$ $f=1.0MHz$	-	5211	-	pF
C_{oss}	Output Capacitance		-	232	-	pF
C_{rss}	Reverse Transfer Capacitance		-	163	-	pF
Q_g	Total Gate Charge	$V_{DS}=30V, I_D=30A,$ $V_{GS}=10V$	-	94	-	nC
Q_{gs}	Gate-Source Charge		-	16	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	24	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=30V, I_D=2A,$ $R_L=15\Omega, R_{GEN}=2.5\Omega,$ $V_{GS}=10V$	-	15	-	ns
t_r	Turn-on Rise Time		-	11	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	52	-	ns
t_f	Turn-off Fall Time		-	13	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current	-	-	59	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	236	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_S=59A$	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	$T_J = 25^\circ C$	-	33	-	ns
Qrr	Body Diode Reverse Recovery Charge		$I_F=28A, dI/dt=100A/\mu s$	-	54	-

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: $T_J=25^\circ C$, $V_{DD}=50V$, $V_G=10V$, $L=0.5mH$, $R_G=25\Omega$, $I_{AS}=19.8A$ 3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

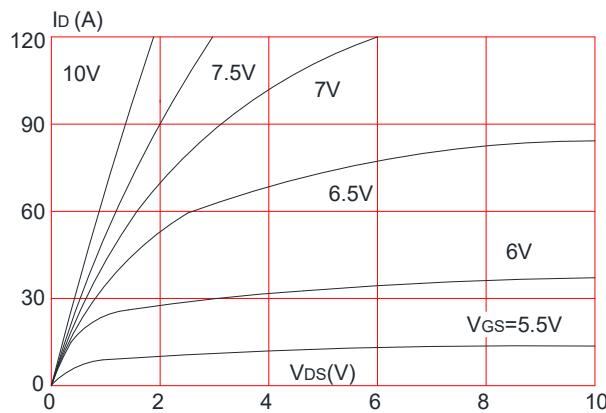


Figure 3: On-resistance vs. Drain Current

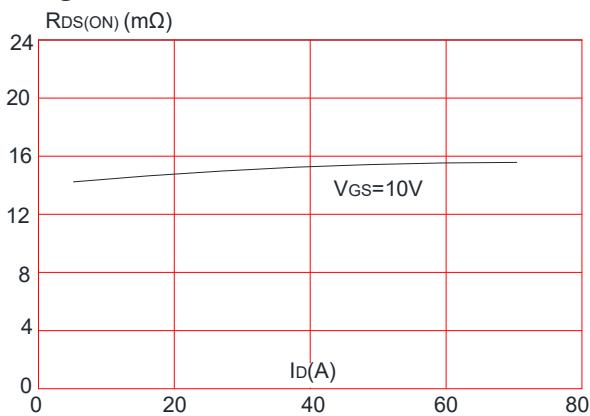


Figure 5: Gate Charge Characteristics

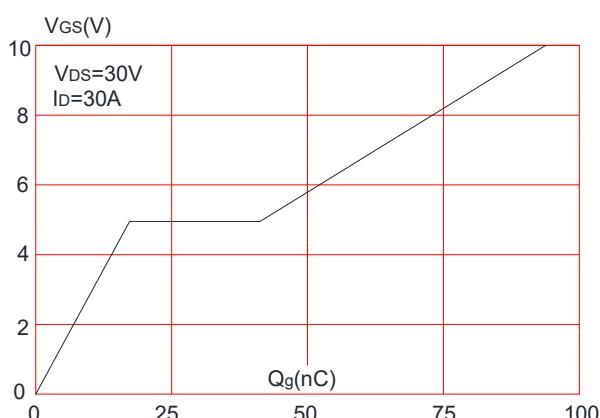


Figure 2: Typical Transfer Characteristics

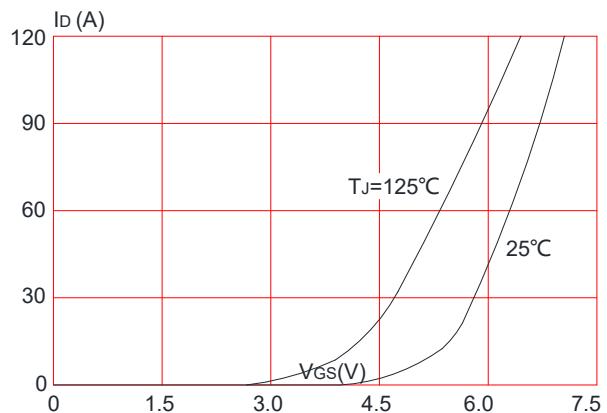


Figure 4: Body Diode Characteristics

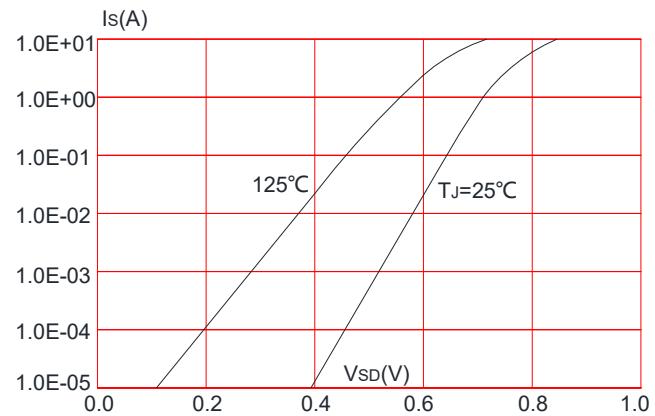


Figure 6: Capacitance Characteristics

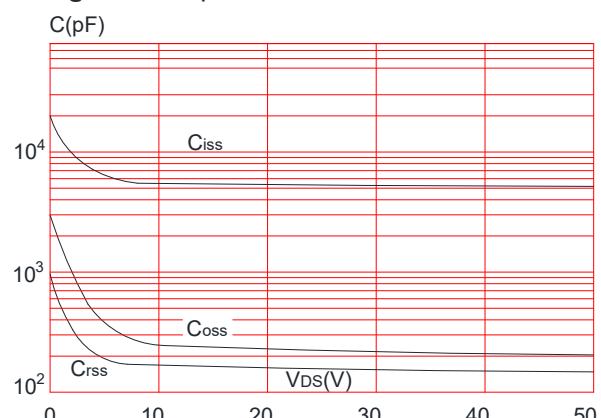


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

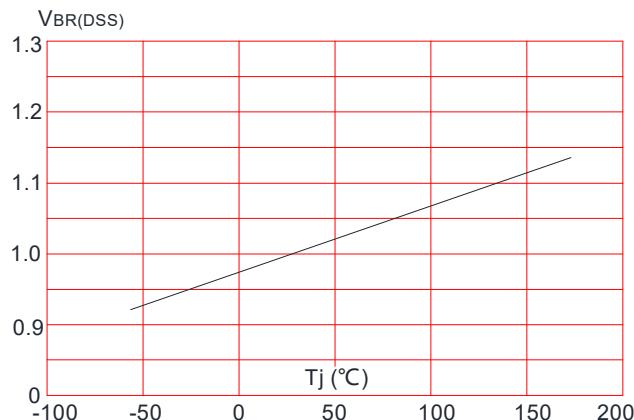


Figure 9: Maximum Safe Operating Area

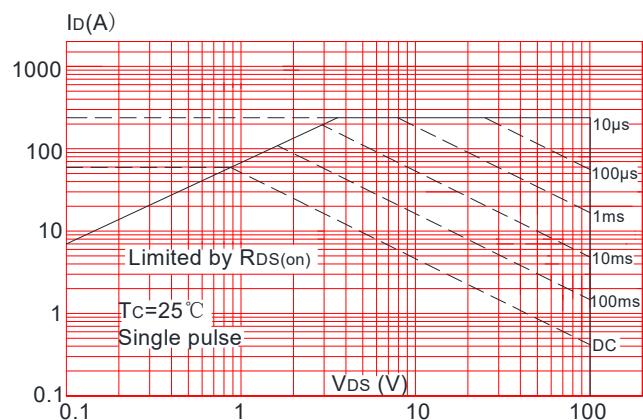


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

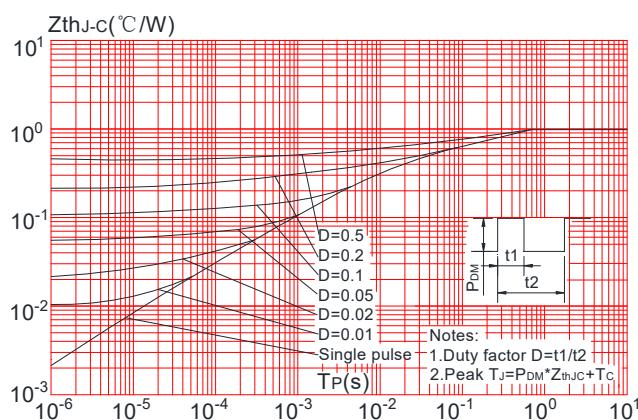


Figure 8: Normalized on Resistance vs. Junction Temperature

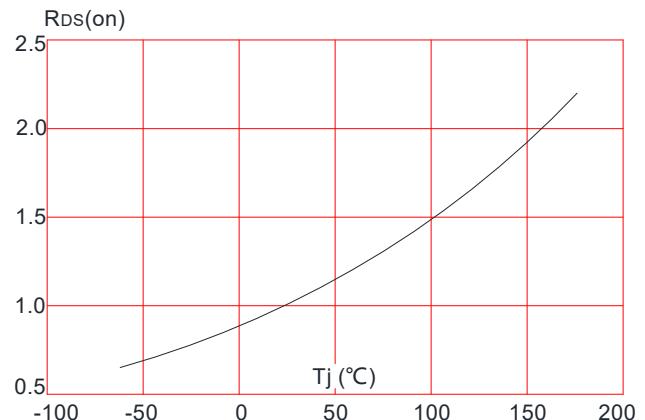
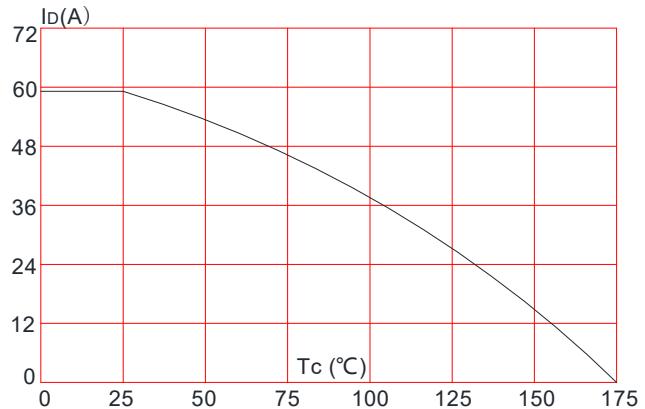


Figure 10: Maximum Continuous Drain Current vs. Case Temperature



Test Circuit

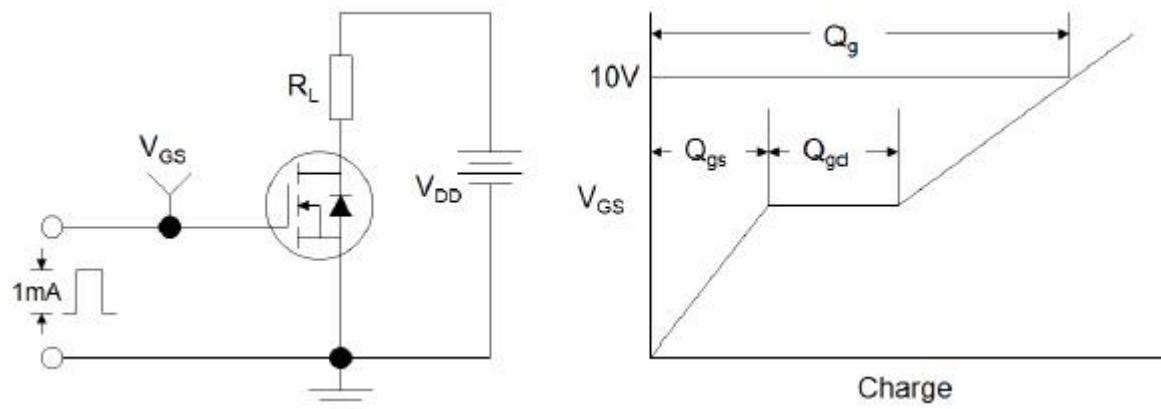


Figure1:Gate Charge Test Circuit & Waveform



Figure 2: Resistive Switching Test Circuit & Waveforms

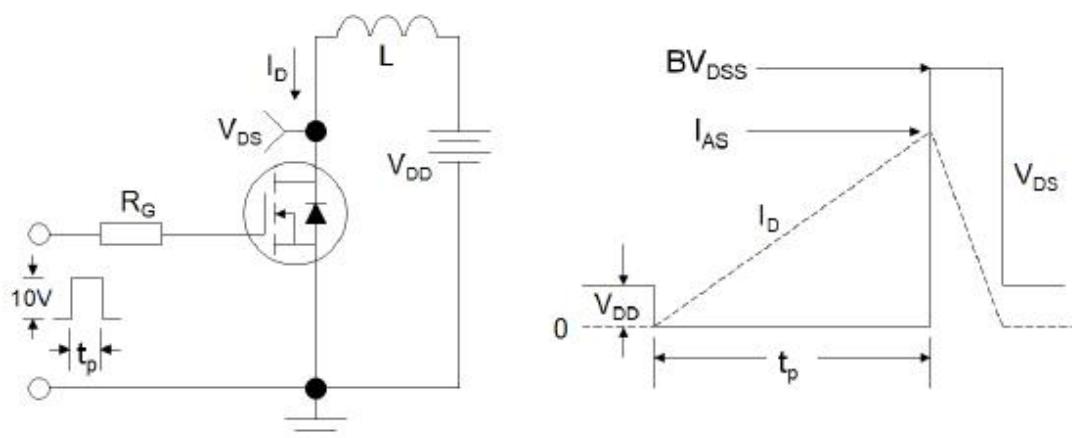
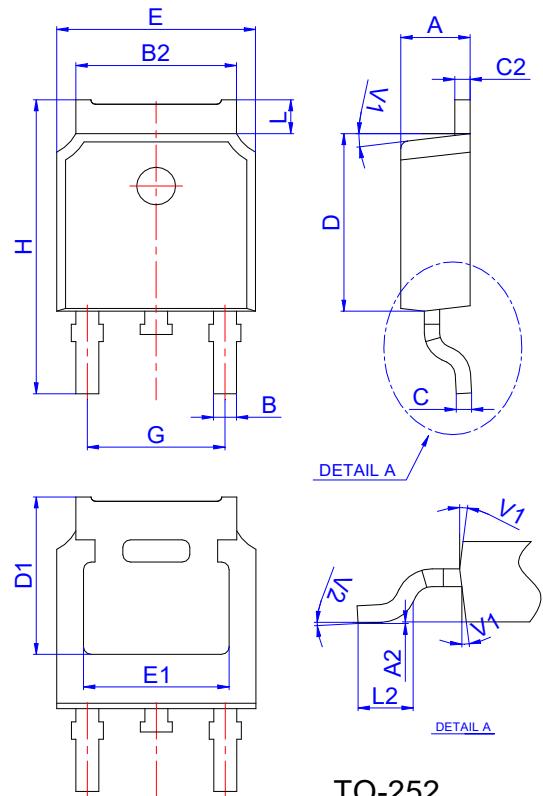


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

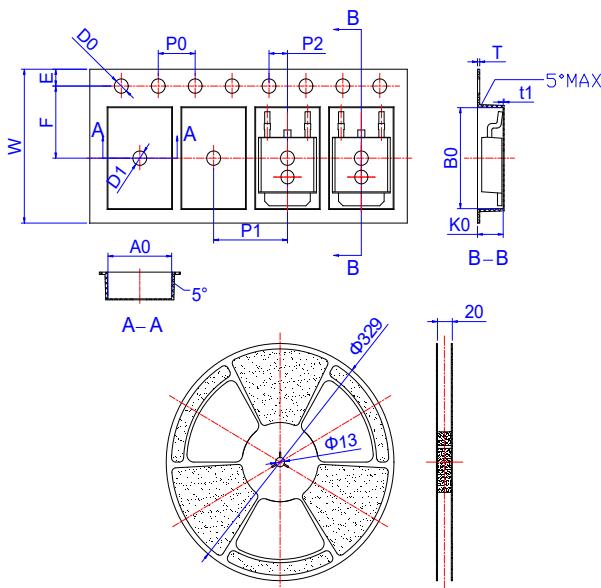
Package Mechanical Data-TO-252-4R



TO-252

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Reel Specification-TO-252-4R



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
B0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583



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